



GE Energy

Functional Testing Specification

*Parts & Repair Operations
Louisville, KY*

LOU-GEF-IC600RM715

Test Procedure for a Series Six RPU Memory card (IC600RM715).

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1. SCOPE

1.1 This is a functional testing procedure for a Series Six RPU Memory card (IC600RM715).

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires: broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors: broken or cracked

4.2.1.3 Components: visually damaged

4.2.1.4 Capacitors: bloated or leaking

4.2.1.5 Solder joints: damaged or cold

4.2.1.6 Circuit board: burned or de-laminated

4.2.1.7 Printed wire runs / Traces: burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1	H188896	RPU-1 Main
1	H188889	CPU Workmaster

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6. **TESTING**

6.1 **Setup**

- 6.1.1 Remove the top cover-shield to verify that all RAM chips are properly seated in the card and to check the battery voltage.
- 6.1.2 Verify that all RAM chips are seated properly in their sockets.
- 6.1.3 Ensure that the battery voltage is no less than 3.2VDC.
- 6.1.4 Ensure that the jumper and dipswitch settings are set in accordance with GEK-84873.
- 6.1.5 Turn off power to RPU-1 Main.
- 6.1.6 Remove the shop card from slot 3 of RPU-1 Main.
- 6.1.7 Install the customer card into slot 3 of RPU-1 Main.

6.2 **Test Process**

- 6.2.1 Turn on power to RPU-1 Main.
- 6.2.2 Ensure that the battery indicator LED lights.
- 6.2.3 Ensure that the Device Switch card (located in slot 8) displays a "1" on its digital readout.
- 6.2.4 Ensure that the Device Switch will toggle between CPU-1 and CPU-2 when selecting CPU-1 or CPU-2 from the "Auto" key switch (located on RPU-1 Main's power supply).
- 6.2.5 Turn off power to RPU-1 Main.
- 6.2.6 Remove the customer card from slot 3 of RPU-1 Main.
- 6.2.7 Install the shop card into slot 3 of RPU-1 Main.
- 6.2.8 Test complete.

7. **NOTES**

- 7.1 None at this time.

8. **ATTACHMENTS**

- 8.1 None at this time.